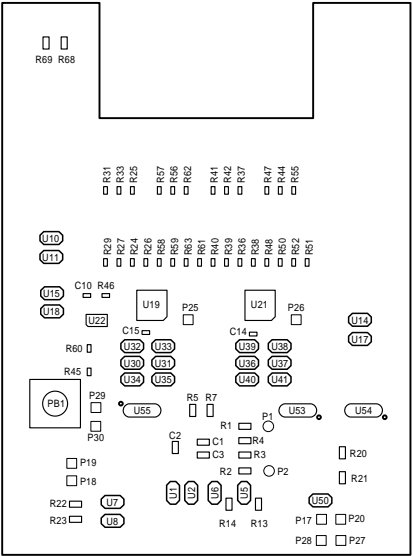
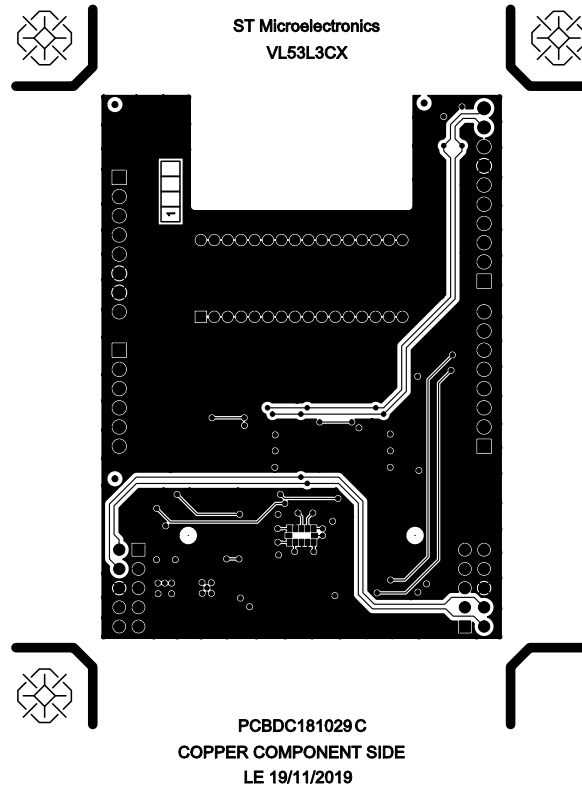
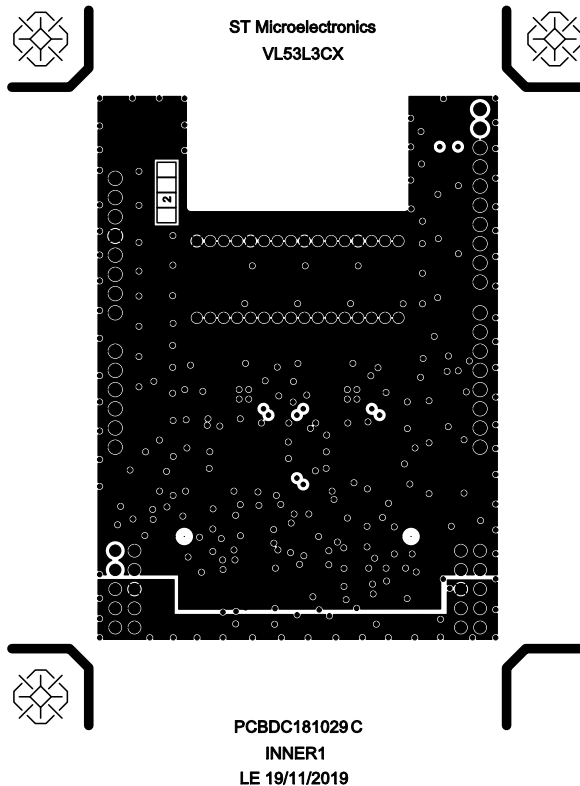


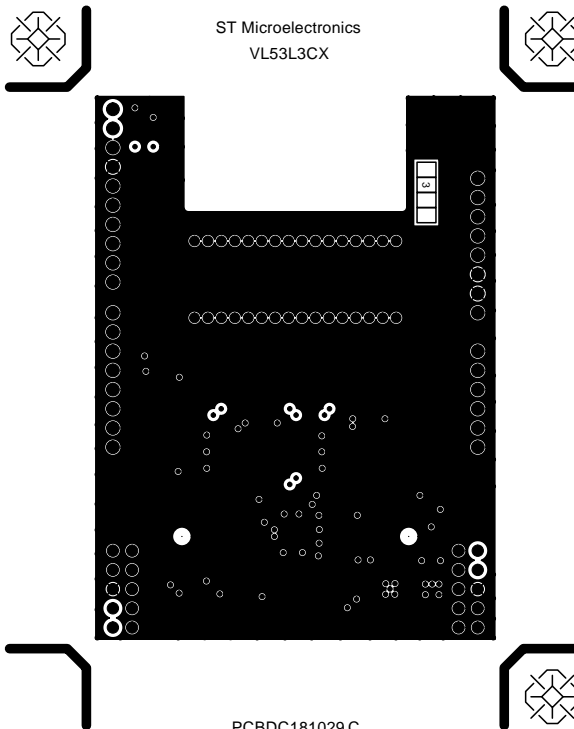
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			SIDE VIEW TOP ASSEMBLY	
			VL53L3A2	
			NUMBER: PCBDC181029C	
			SCALE: 1:1	SHEET: 1/1
			DESIGN DATE: 19/11/2019	DESIGNER:PTS



IE	DATE	MODIFICATION	ST MICROELECTRONICS	
			SIDE VIEW	BOTTOM ASSEMBLY
			VL53L3A2	
			NUMBER:PCBDC181029C	
			SCALE: 1/1	SHEET: 1/1
			DESIGN DATE: 19/11/2019	DESIGNER: PTS

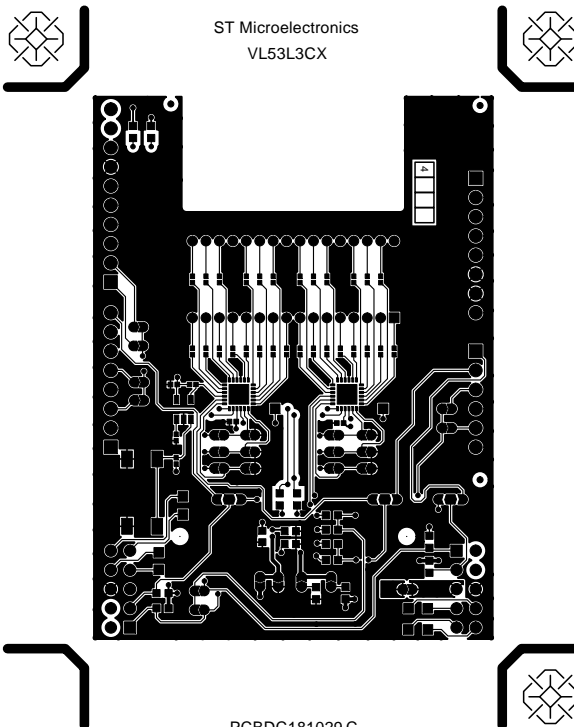






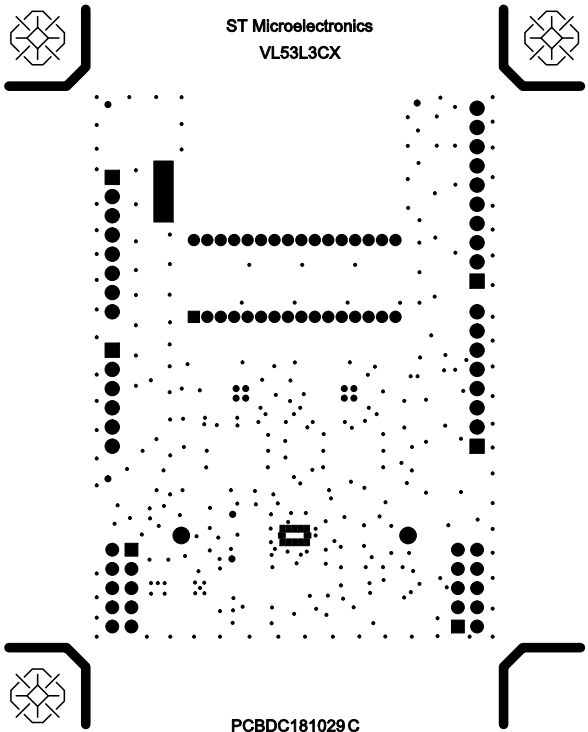
ST Microelectronics
VL53L3CX

PCBDC181029 C
INNER2
LE 19/11/2019



ST Microelectronics
VL53L3CX

PCBDC181029 C
COPPER SOLDER SIDE
LE 19/11/2019

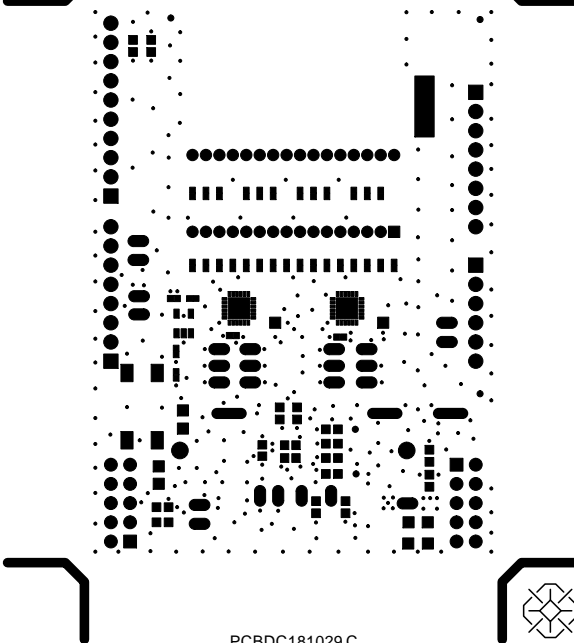


ST Microelectronics
VL53L3CX

PCBDC181029 C
SOLDER RESIST COMPONENT SIDE
LE 19/11/2019

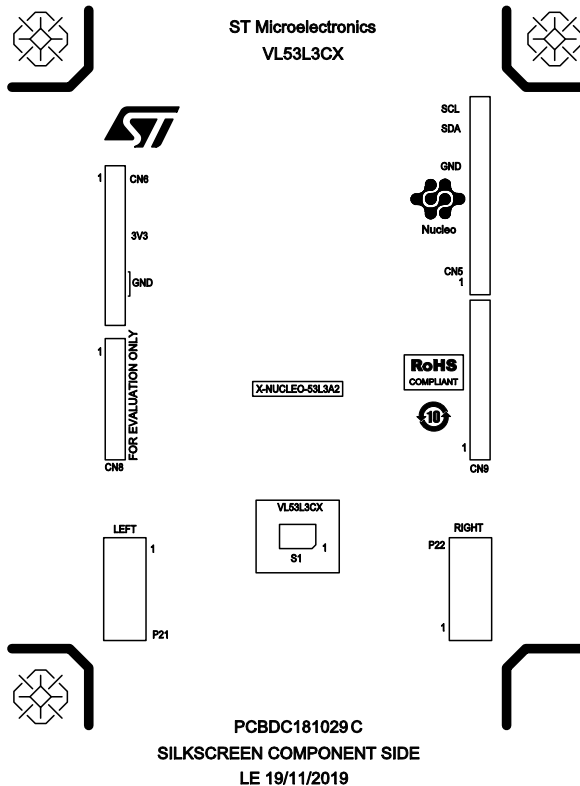


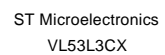
ST Microelectronics
VL53L3CX



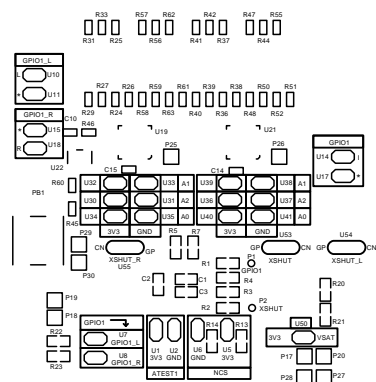
PCBDC181029 C
SOLDER RESIST SOLDER SIDE
LE 19/11/2019







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PCBDC181029 C
SILKSCREEN SOLDER SIDE
LE 19/11/2019



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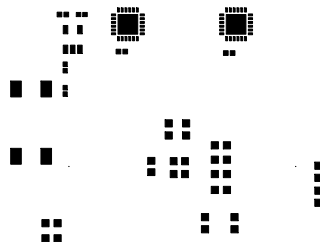


PCBDC181029 C
PASTEMASK COMPONENT SIDE
LE 19/11/2019





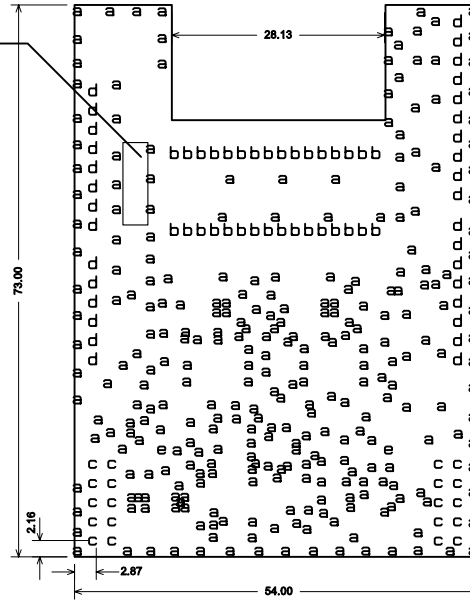
ST Microelectronics
VL53L3CX



PCBDC181029 C
PASTEMASK SOLDER SIDE
LE 19/11/2019



MANUFACTURING DATE CODE
MARK CUSTOMER ON BOTTOM
SOLDER MASK



DRILL TABLE

DRILLING THROUGH HOLES

SYMBOLE	DIAMETRE	NBR	PRECISION	METAL
a	0.3	295	VIA	YES
b	0.75	32	+/- 0.05	YES
c	0.9	20	+/- 0.05	YES
d	1.1	32	+/- 0.05	YES
e	2.0	2	+/- 0.05	NO

CROSS SECTION

1	Cu 35µm
2	Prepreg 2113
3	Core
4	Prepreg 2113
5	Cu 35µm

SIGNAL 50 OHMS :
LAYERS 1 & 4 -> TRACKS 150µm
PLANE REF
LAYER 1 -> LAYER 2
LAYER 3 -> LAYER 4

BOARD SPECIFICATION

CIRCUIT : 4 LAYERS
CLASS : 5
MATERIAL : FR4 TG150 VT47
SIZE CIRCUIT : 73mm X 54 mm
THICKNESS CIRCUIT : 1.6 mm
FINISH : NiAu Chimique
SOLDER RESIST : BLUE COLOR
☒ TOP ☒ BOTTOM
SILKSCREEN : WHITE COLOR
☒ TOP ☒ BOTTOM
DRILLING :
VIA PTH MINIMUM : 0.30mm

IE	DATE	MODIFICATION	ST MICROELECTRONICS	
			SIDE VIEW TOP ASSEMBLY	
			VL53L3A2	
			DRILLING THROUGH HOLES	
			NUMBER: PCBDC181029C	
			SCALE: 1:1	SHEET: 1/1
			DESIGN DATE: 19/11/2019	DESIGNER:PTS